

ABSTRACT OF THE DISCLOSURE

A method and apparatus for forming a dielectric layer. A dielectric precursor solution is deposited onto a surface of a substrate. The substrate is spun to spread the dielectric precursor solution over the surface of the substrate. A catalyst is introduced through a filter, wherein the filter causes a substantially homogenous distribution of the catalyst within the substrate, wherein a dielectric layer forms containing pores and wherein a solvent is contained in the pores. The solution is dried to form the dielectric layer using a carrier gas after introducing the catalyst, wherein the carrier gas places a positive pressure within the pores while removing the solvent to form a low-k dielectric layer.